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THIN SEMICONDUCTOR PACKAGE INCLUDING STACKED DIES

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ABSTRACT

A semiconductor package is disclosed that includes multiple combinations of stacked or side by side semiconductor chips, at least one of which is at least partially disposed within a through hole formed in a substrate. Another embodiment includes a package with a metal core for improving mechanical strength, heat dissipation, electrical grounding, and power distribution characteristics of the packages. The substrate may be configured to facilitate stacking additional semiconductor packages.

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